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Customer No.: 31561  
Application No.: 10/604,791  
Docket No.: 9249-US-PA

### Remarks

To response to the Restriction Requirement, Applicants have elected to continue prosecution in this application on Embodiment I described in Fig. 2 to Fig. 6, drawn to claims 1-20 with traverse.

As stated in MPEP Chapter 806.03, when the claims of an application define the same essential characteristics of a single disclosed embodiment of an invention, restriction therebetween should never be required. This is because the claims are basically different definitions of the same disclosed subject matter, varying in breadth or scope. The alleged species (1) (corresponding to Embodiment 1), the alleged species (2) (corresponding to Embodiment 2) and the alleged species (3) (corresponding to Embodiment 3) of the present invention are directed to a process for fabricating a multi-chip package module, wherein the packaging material enclosing the multiple chips, the conductive wires and the bumps is formed in one encapsulation step. The alleged species (1) of the invention is drawn to a multi-chip package module fabricating process comprising providing a first chip and providing a package body having a plurality of bumps. The alleged species (2) of the invention is drawn to a multi-chip package module fabricating process also comprising providing a first chip and providing a package body having a plurality of bumps, wherein the package body comprises a second chip, a carrier, a plurality of additional bumps and

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an underfill material. The alleged species (3) of Group II is drawn to a multi-chip package module fabricating process also comprising providing a first chip and providing a package body having a plurality of bumps, wherein the package body comprises a second chip, a carrier, a plurality of additional conductive wires and an additional packaging material.

In other words, the alleged species (1) (2) and (3) teaches forming providing a first chip and providing a package body, wherein the package body can further includes a second chip, conductive wires or bumps. The alleged species (1), (2) and (3) of the present invention are thus neither mutually exclusive, independent nor distinct, and they are unable to support separate patents. Instead, these alleged species vary only in breath and scope. A restriction to one thereof is thereby not proper.

In addition, since claim 11-20 include no material element or limitation additional to those recited in the claims 21-22 or claims 23-24, and the confines of claim 11 are covered in each of the alleged species, Applicants respectfully submit that claim 11 is qualified as a generic claim.

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No fee is believed to be due in connection with the filing of this paper. However, the Commissioner is authorized to charge any additional fees that may be required to Account no. 50-2620 (Order No. 9249-US-PA).

Respectfully submitted,

Date :

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